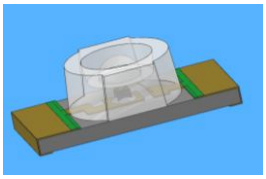
DATASHEET

1026 Package Chip LED with Inner Lens

HIR25-21C/L423/2T



Features

- Small double-end package
- Low forward voltage
- Good spectral matching to Si photo detector
- Package in 8mm tape on 7″ diameter reel.
- Pb free
- The product itself will remain within RoHS compliant version.
- Compliance with EU REACH
- Compliance Halogen Free .(Br <900 ppm ,Cl <900 ppm , Br+Cl < 1500 ppm).

Descriptions

- HIR25-21C/L423/2T is an infrared emitting diode
  in miniature SMD package which is molded in a water clear plastic
  with spherical top view lens.
  The device is spectrally matched with silicon photodiode and phototransistor

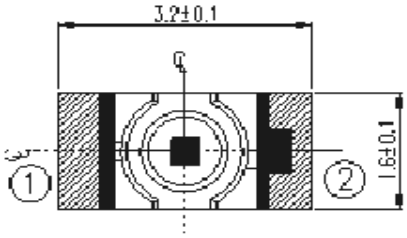
Applications

- PCB mounted infrared sensor
- Infrared remote control units with high power requirement
- Scanner
- Infrared applied system

Device Selection Guide

Part Category	Chip Material	Lens Color
HIR	GaAlAs	Water clear

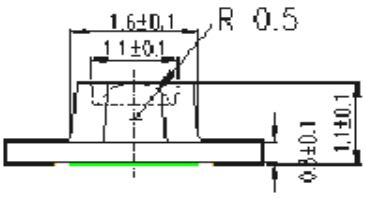
Package Dimensions



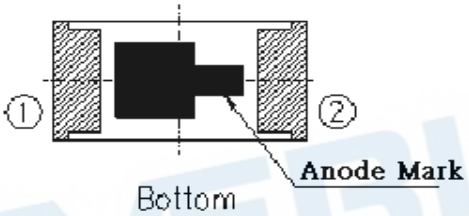
Top

Polarity

① Cathode
② Anode

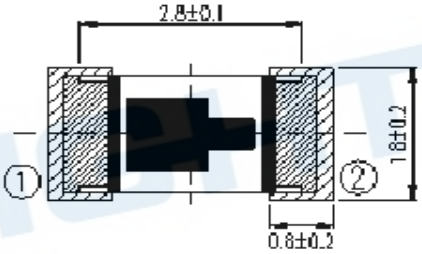


Side



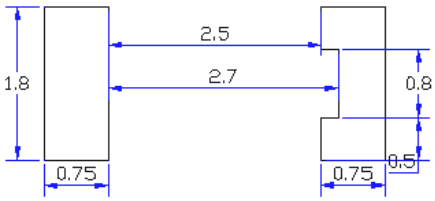
Bottom

Recommend Sodering Pad



Suggested pad dimension is just for reference only.
Please modify the pad dimension based on individual need.

Notes: 1.All dimensions are in millimeters
2.Tolerances unless dimensions ±0.1mm
3.Suggested pad dimension is just for reference only
.Please modify the pad dimension based on individual need



4.Suggested pad dimension is just for reference only
Please modify the pad dimension based on individual need

Absolute Maximum Ratings (Ta=25℃)

Parameter	Symbol	Rating	Units
Continuous Forward Current	I_F	50	mA
Peak Forward Current(300pps,10us pulse)	I_{FP}	800	mA
Reverse Voltage	V_R	5.0	V
Operating Junction Temperature	Tj	105	℃
Operating Temperature	T_{opr}	-40 ~ +85	℃
Storage Temperature	T_{stg}	-40 ~ +85	℃
Soldering Temperature	T_{sol}	260	℃
Total Power Dissipation	P_t	100	mW
Power Dissipation at(or below) 25℃Free Air Temperature	P_d	110	mW

Electro-Optical Characteristics (Ta=25℃)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Units
Radiant Intensity	Ie	I_F=20mA	3.0	5.5	9.0	mW/sr
Peak Wavelength	λp	I_F=20mA	--	850	--	nm
Spectral Bandwidth	Δλ	I_F=20mA	--	42	--	nm
Forward Voltage	V_F	I_F=50mA	1.30	1.60	2.00	V
Reverse Current	I_R	V_R=5V	--	--	10	μA
Optical rise and fall time	t_r/t_f	I_F=20mA	--	25/15	35/35	ns
View Angle	2θ1/2	I_F=20mA	--	70	--	deg

Typical Electro-Optical Characteristics Curves

Fig.1 Forward Current vs. Ambient Temperature

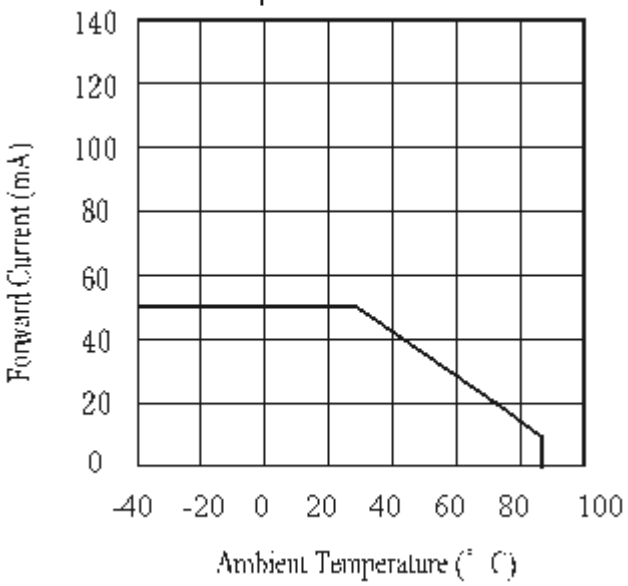


Fig.2 Spectral Distribution

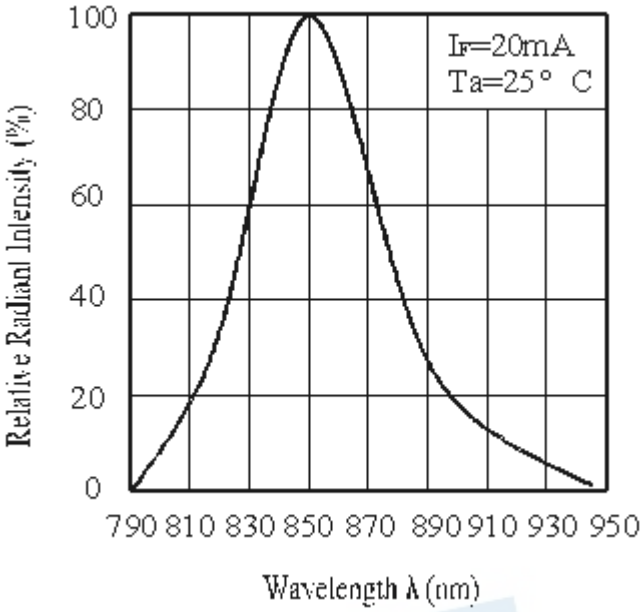


Fig.3 Forward Current vs. Forward Voltage

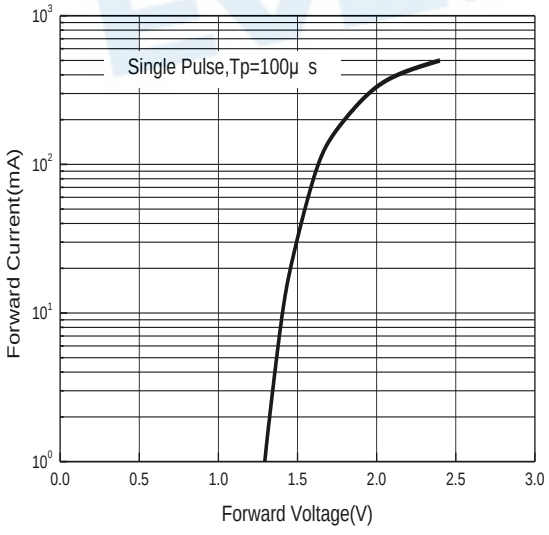
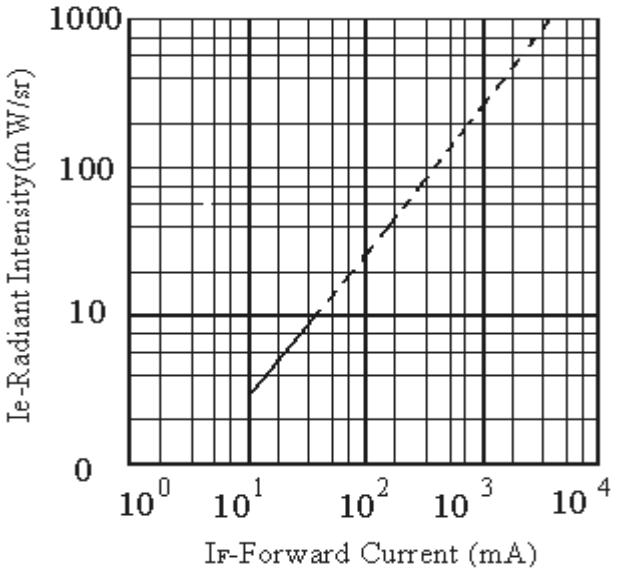
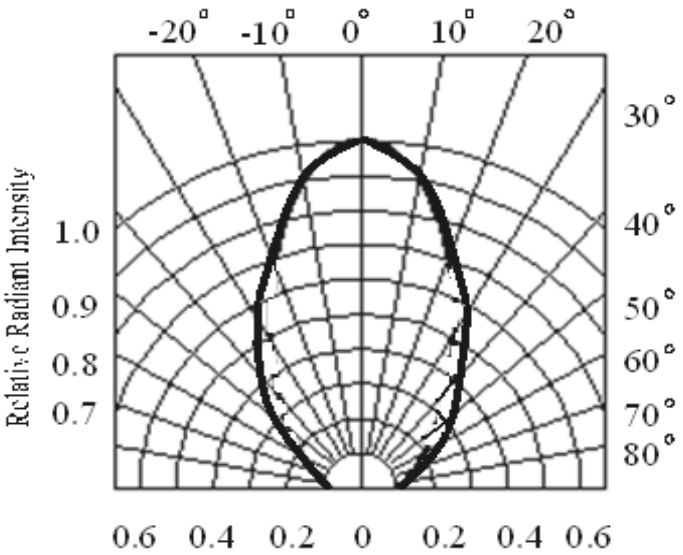


Fig.5 Radiant Intensity vs. Forward Current



Typical Electro-Optical Characteristics Curves

Fig.6 Relative Radiant Intensity vs.
Angular Displacement



Precautions For Use

1. Over-current-proof

   Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

   2.1 Do not open moisture proof bag before the products are ready to use.

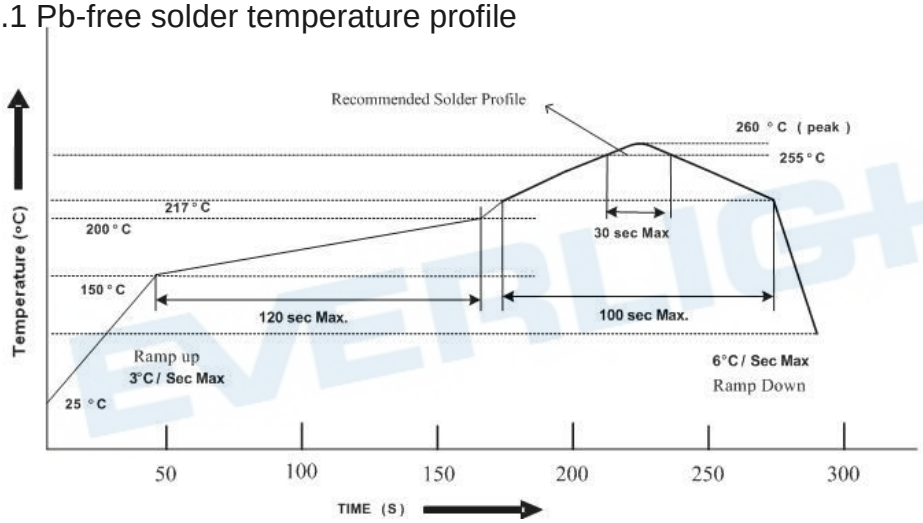
   2.2 After opening the package: The LEDs should be kept at 30℃ or less and 60%RH or less.

   2.3 The LEDs should be used within 168 hours (7days) after opening the package .

   2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions. Baking treatment : 60±5℃ for 24 hours.

3. Soldering Condition

   3.1 Pb-free solder temperature profile



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

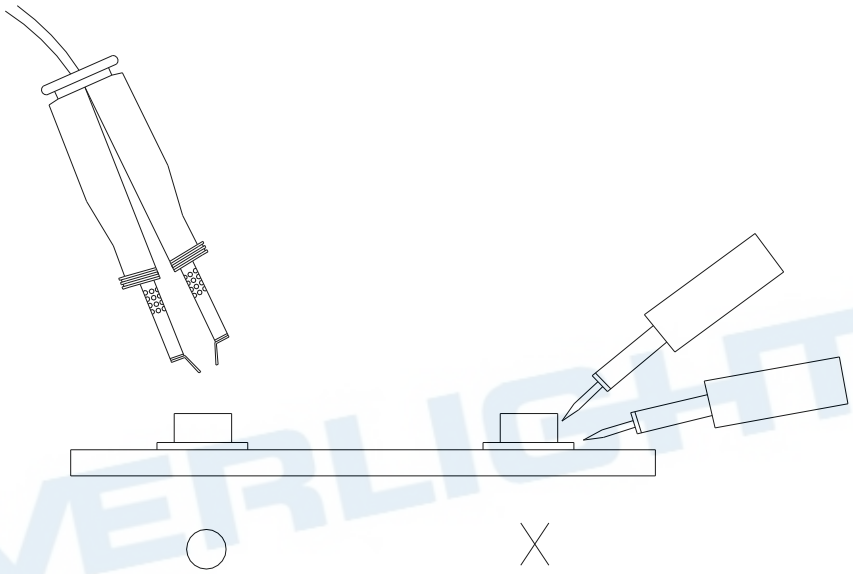
3.4 After soldering, do not warp the circuit board.

4.Soldering Iron

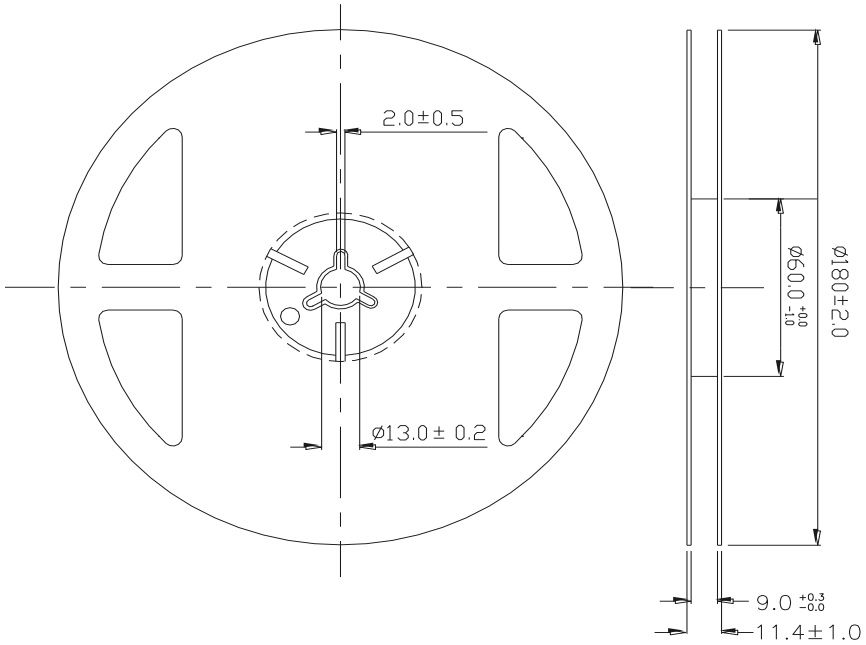
Each terminal is to go to the tip of soldering iron temperature less than350℃ for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5.Repairing

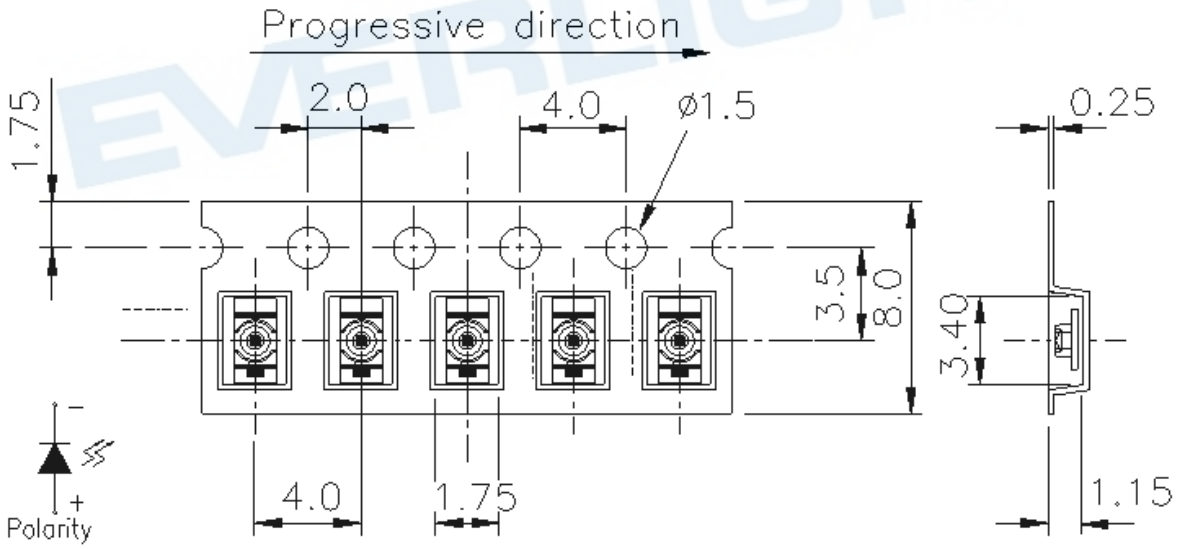
Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



Package Dimensions

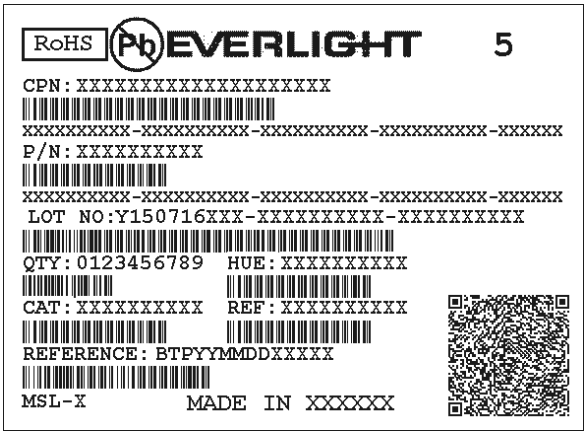


Carrier Tape Dimensions: Loaded quantity 2000 PCS per reel



Note: The tolerances unless mentioned is ±0.1mm ,Unit = mm

Label Form Specification



CPN: Customer's Production Number
P/N : Production Number
LOT No: Lot Number
QTY: Packing Quantity
HUE: Peak Wavelength
CAT: Ranks
REF: Reference
MSL-X: MSL Level
Made In: Manufacture place

DISCLAIMER

1. EVERLIGHT reserves the right(s) on the adjustment of product material mix for the specification.
2. The product meets EVERLIGHT published specification for a period of twelve (12) months from date of shipment.
3. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
4. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from the use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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